



1Mx8 CMOS SRAM MONOLITHIC

FEATURES

- 1 Meg x 8 bit CMOS Static
- Random Access Memory
 - Access Times 55 thru 100ns
 - Data Retention Function (EDI8F81027LP)
 - TTL Compatible Inputs and Outputs
 - Fully Static, No Clocks
- High Density Packaging
 - 32 Pin DIP, No.
- Single +5V ($\pm 10\%$) Supply Operation

DESCRIPTION

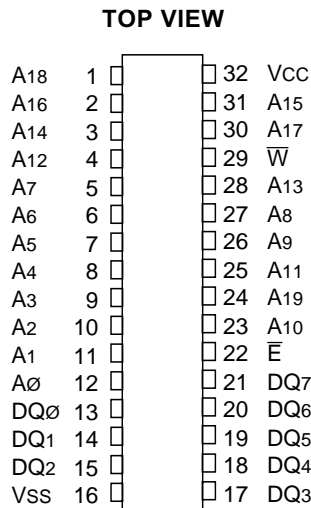
The EDI8F81027C is an 8 megabit CMOS Static RAM based on two 512Kx8 Static RAMs mounted on a multi-layered epoxy laminate (FR4) substrate.

A low power version with data retention (EDI8F81027LP) is also available.

All inputs and outputs are TTL compatible and operate from a single 5V supply.

Fully asynchronous, the EDI8F81027C requires no clocks or refreshing for operation.

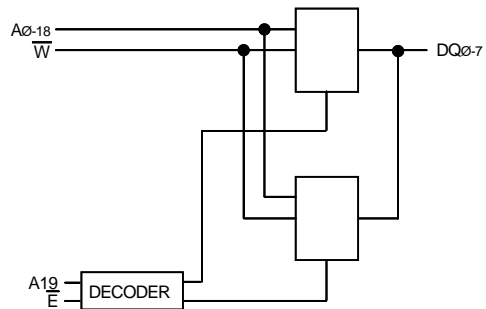
FIG. 1 PIN CONFIGURATION



PIN DESCRIPTION

A $\bar{0}$ -19	Address Inputs
\bar{E}	Chip Enable
\bar{W}	Write Enable
DQ $\bar{0}$ -7	Common Data Input/Output
V _{CC}	Power (+5V $\pm 10\%$)
V _{SS}	Ground
NC	No Connection

BLOCK DIAGRAM





ABSOLUTE MAXIMUM RATINGS*

Voltage on any pin relative to Vss	-0.5V to 7.0V
Operating Temperature TA (Ambient)	
Commercial	0°C to +70°C
Industrial	-40°C to +85°C
Storage Temperature	-55°C to +125°C
Power Dissipation	1 Watt
Output Current	20 mA

*Stress greater than those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions greater than those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

TRUTH TABLE

\bar{G}	\bar{E}	\bar{W}	Mode	Output	Power
X	H	X	Standby	High Z	Icc2, Icc3
H	L	H	Output Deselect	High Z	Icc1
L	L	H	Read	DOUT	Icc1
X	L	L	Write	DIN	Icc1

RECOMMENDED DC OPERATING CONDITIONS

Parameter	Sym	Min	Typ	Max	Units
Supply Voltage	Vcc	4.5	5.0	5.5	V
Supply Voltage	Vss	0	0	0	V
Input High Voltage	VIH	2.2	--	6.0	V
Input Low Voltage	VIL	-0.3	--	0.8	V

AC TEST CONDITIONS

Input Pulse Levels	Vss to 3.0V
Input Rise and Fall Times	5ns
Input and Output Timing Levels	1.5V
Output Load	1TTL, CL = 100pF

(Note: For tEH0Z, tGH0Z and tWL0Z, CL = 5pF)

CAPACITANCE

(f = 1.0MHz, VIN = Vcc or Vss)

Parameter	Symbol	Max	Unit
Address Lines	CI	30	pF
Data Lines	CD/O	43	pF
Chip Enable Line	Cc	10	pF
Write and Output Enable Lines	Cw	32	pF

These parameters are sampled, not 100% tested.

DC ELECTRICAL CHARACTERISTICS

Parameter	Symbol	Conditions	Min	Typ*	Max	Units	
Operating Power Supply Current	Icc1	$\bar{W}, \bar{E} = V_{IL}, I_{I/O} = 0mA,$ Min Cycle	--	85	175	mA	
Standby (TTL) Power Supply Current	Icc2	$\bar{E} \geq V_{IH}, V_{IN} \leq V_{IL}$ $V_{IN} \geq V_{IH}$	--	25	55	mA	
Full Standby Power Supply Current (CMOS)	Icc3	$\bar{E} \geq V_{CC} - 0.2V$ $V_{IN} \geq V_{CC} - 0.2V$ or $V_{IN} \leq 0.2V$	C	--	1.5	2	mA
			LP	--	190	300	µA
Input Leakage Current	ILI	VIN = 0V to VCC	-10	--	10	µA	
Output Leakage Current	ILO	V _{I/O} = 0V to VCC	-10	--	10	µA	
Output High Voltage	VOH	I _{OH} = -1.0mA	2.4	--	--	V	
Output Low Voltage	VOL	I _{OL} = 2.1mA	--	--	0.4	V	

*Typical: TA = 25°C, Vcc = 5.0V



AC CHARACTERISTICS - READ CYCLE

Parameter	Symbol		55ns		70ns		85ns		100ns		Units
	JEDEC	Alt.	Min	Max	Min	Max	Min	Max	Min	Max	
Read Cycle Time	tAVAV	trc	55		70		85		100		ns
Address Access Time	tAVOQ	tAA		55		70		85		100	ns
Chip Enable Access Time	tELOV	tACS		55		70		85		100	ns
Chip Enable to Output in Low Z (1)	tELOX	tCLZ	5		5		5		5		ns
Chip Disable to Output in High Z (1)	tEHOZ	tCHZ		25		30		35		40	ns
Output Hold from Address Change	tAVOX	toH	5		5		5		5		ns

NOTE:

1. Parameter guaranteed, but not tested.

AC CHARACTERISTICS - WRITE CYCLE

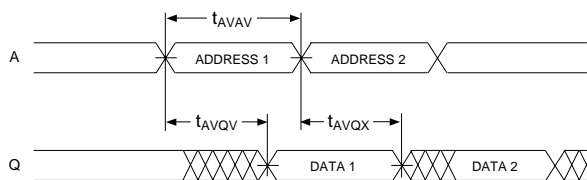
Write Cycle Parameter	Symbol		55ns		70ns		85ns		100ns		Units
	JEDEC	Alt.	Min	Max	Min	Max	Min	Max	Min	Max	
Write Cycle Time	tAVAV	tWC	55		70		85		100		ns
Chip Enable to End of Write	tELWH	tCW	50		65		70		80		ns
	tELEH	tCW	50		65		70		80		ns
Address Setup Time	tAVWL	tAS	0		0		0		0		ns
	tAVEH	tAS	0		0		0		0		ns
Address Valid to End of Write	tAVWH	tAW	50		65		70		80		ns
	tAVEH	tAW	50		65		70		80		ns
Write Pulse Width	tWLWH	tWP	45		65		70		80		ns
	tWLEH	tWP	45		65		70		80		ns
Write Recovery Time	tWHAX	tWR	5		5		5		5		ns
	tEHAX	tWR	5		5		5		5		ns
Data Hold Time	tWHDX	tDH	0		0		0		0		ns
	tEHDX	tDH	0		0		0		0		ns
Write to Output in High Z (1)	tWLOZ	tWHZ	25	0	30	0	35	0	40	0	ns
Data to Write Time	tdWWH	tdW	25		30		35		40		ns
	tdVEH	tdW	25		30		35		40		ns
Output Active from End of Write (1)	tWHQX	tWLZ	5		5		5		5		ns

NOTE:

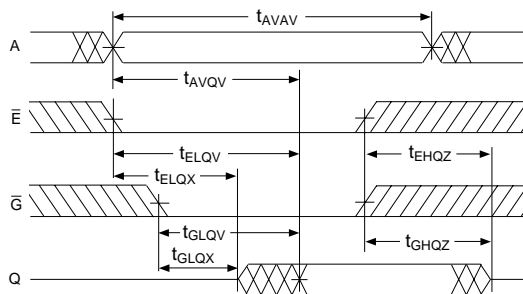
1. Parameter guaranteed, but not tested.



**FIG. 2
READ CYCLES**

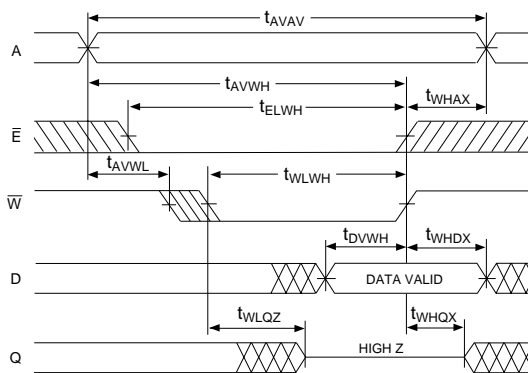


READ CYCLE 1 (\bar{W} HIGH; \bar{G} , \bar{E} LOW)



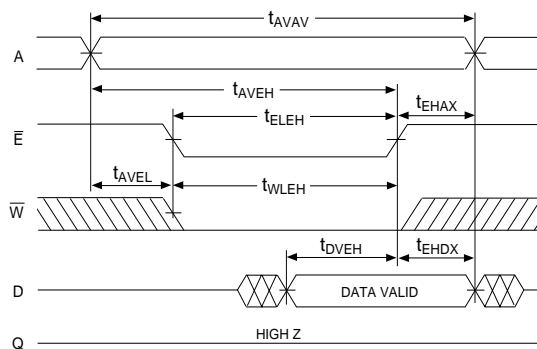
READ CYCLE 2 (\bar{W} HIGH)

**FIG. 3
WRITE CYCLE 1**



WRITE CYCLE 1, \bar{W} CONTROLLED

**FIG. 4
WRITE CYCLE 2**



WRITE CYCLE 2, \bar{E} CONTROLLED



DATA RETENTION CHARACTERISTICS (LP VERSION ONLY)

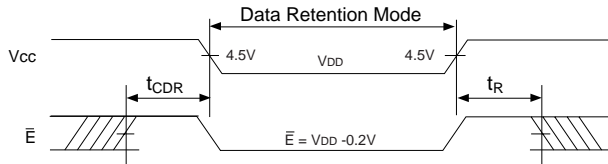
Characteristic	Sym	Test Conditions	V _{DD}	Min	Typ	Max		Unit
						70°C	85°C	
Data Retention Voltage	V _{DD}	$\bar{E} \geq V_{DD} - 0.2V$ $V_{IN} \geq V_{DD} - 0.2V$ or $V_{IN} \leq 0.2V$		2	--	--	--	V
Data Retention Quiescent Current	I _{CCDR}		2V	--		100	130	μA
			3V	--		160	210	μA
Chip Disable to Data Retention Time	t _{CDR} (1)				0	--	--	--
Operation Recovery Time	t _R (1)			t _{AVAV} *	--	--	--	ns

NOTE:

1. Parameter guaranteed, but not tested

* Read Cycle Time

FIG. 5
DATA RETENTION - \bar{E} CONTROLLED



DATA RETENTION, \bar{E} CONTROLLED



ORDERING INFORMATION

Standard Power	Low Power with Data Retention	Speed (ns)	Package No.
EDI8F81027C55B6C	EDI8F81027LP55B6C	55	352
EDI8F81027C70B6C	EDI8F81027LP70B6C	70	352
EDI8F81027C85B6C	EDI8F81027LP85B6C	85	352
EDI8F81027C100B6C	EDI8F81027LP100B6C	100	352
EDI8F81027C70B6I		70	352
EDI8F81027C85B6I		85	352
EDI8F81027C100B6I		100	352

NOTE: To order an Industrial grade product substitute the letter C in the Suffix with the letter I, eg. EDI8F81027C70B6C becomes EDI8F81027C70B6I.

PACKAGE DESCRIPTION

PACKAGE NO. 352
32 PIN DIP

